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AN 85:81944 HCA
TI Effect of trace elements on the recrystallization behavior of high
purity oxygen-containing copper
AU Dierckxsens, Robert
CS Ing. Div., Metall. Hoboken-Overpelt, Olen, Belg.
SO Erzmetall (1975), 28(11), 496-500
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DT Journal
LA German
AB Effect of ppm addns. of Ag, As, Bi, Pb, S, Sb
, Se, and Te on the recrystn. behavior of 99.
999% Cu was detd. after annealing at 600 or 800.degree.
and drawing 97.4%. The alloying addns. were above and below those
usually
experienced in Cu processing. The temp. for .apprx.50%
recrystn. was detd. from the hardness decrease during annealing.
Recrystn. temps. of 116-250.degree. were detd. Highest value was
obtained
by adding Te, Pb, Se, or Sb. Two methods were
developed for relating the obsd. changes to the amt. of each trace
element
when more than one was present.